



Board Characteristics - 6 LAYER BOARD

0. All dimensions are given in inches unless specified otherwise.
1. Material FR4
2. Minimum trace width and clearance: 0.006"
4. 1 oz copper for all layers.
5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um.
6. Apply Solder Mask over bare copper.
8. Silkscreen on Component and Solder Sides.
10. FHS tolerances: +/- 0.003 unless specified otherwise.
11. Interlayer spacing as specified

BOARD's DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.014	732	YES	---	
⊞	.035	8	YES	---	
⊘	.041	73	YES	---	
⊞	.042	20	YES	---	
⊖	.057	8	YES	---	
⊞	.098425197	2	YES	---	
⊕	.104	2	YES	---	
□	.106	4	NO	---	
	.15	3	NO	---	
	.2	2	YES	---	

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP					
			APPROVALS		DATE	TITLE				
TREATMENT			DRAWN M. Bogdan		5/5/10		ASIC Tester Board Specification Drawing			
FINISH			CHECKED M. Bogdan		5/5/10		SIZE	FSCM NO.	DRG. NO. 2677	REV. A
SIMILAR TO			ACT. WT	CALC WT			SCALE 1/2	SHEET		